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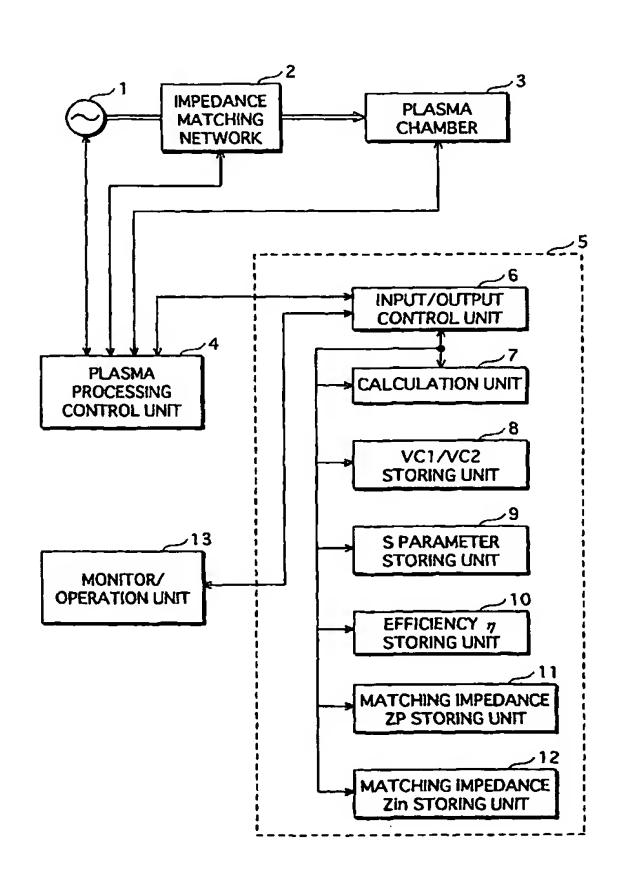
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(54) Title: PLASMA PROCESSING APPARATUS, CONTROL METHOD FOR PLASMA PROCESSING APPARATUS, AND EVALUATION METHOD FOR PLASMA PROCESSING APPARATUS



(57) Abstract: A plasma processing apparatus comprises: an RF generator (1) operable to output RF power; an impedance matching network (2) operable to receive the RF power; a plasma chamber (3) operable to receive an output from the impedance matching network (2); a storing unit (5) operable to store information relating to an S parameter of the impedance matching network (2); and a control unit (4) operable to control an operating condition for the plasma chamber (3), based on the information relating to the S parameter.

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